BS89

LiPOLY
SHIU LI TECHNOLOGY CO.,LTD

Exceptionally Soft Thermal Conductive Gel Pad

LiPOLY BS89 is an ultra-soft thermally conductive gel pad with a thermal conductivity of 5.0 W/m*K.BS89 offers excellent compression under minimal force with high recovery characteristics. This product can be supplied as standard sheets, custom die-cuts or custom molded parts.

FEATURES

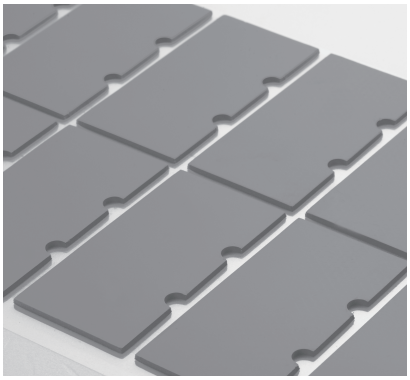
/ Thermal conductivity: 5.0 W/m*K
/ High compression rate
/ Low thermal impedance
/ High recovery
/ Available in a range of thicknesses

TYPICAL APPLICATION

/ Between CPU and heat sink
/ Between a component and heat sink
/ Notebook computers
/ Power supplies
/ High speed mass storage drives
/ Telecommunication hardware

SPECIFICATIONS

/ Sheet form
/ Die-cut parts



TYPICAL PROPERTIES

PROPERTY	BS89	TEST METHOD	UNIT
Color	Gray	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	3.0	ASTM D792	g/cm³
Hardness	25	ASTM D2240	Shore OO
Application temperature	-60~180	-	°C
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	29	ASTM D5470 modify	%
Deflection @20 psi	39	ASTM D5470 modify	%
Deflection @30 psi	47	ASTM D5470 modify	%
Deflection @40 psi	52	ASTM D5470 modify	%
Deflection @50 psi	56	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	8	ASTM D149	KV/mm
Surface resistivity	$>10^{11}$	ASTM D257	Ohm
Volume resistivity	$>10^{10}$	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	5.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.318	ASTM D5470	°C-in²/ W
Thermal impedance@20 psi	0.266	ASTM D5470	°C-in²/ W
Thermal impedance@30 psi	0.233	ASTM D5470	°C-in²/ W
Thermal impedance@40 psi	0.211	ASTM D5470	°C-in²/ W
Thermal impedance@50 psi	0.194	ASTM D5470	°C-in²/ W

Thermal Resistance vs. Pressure vs. Deflection